FASTSWITCH HOLLOW-EMITTER NPN TRANSISTORS

- HIGH SWITCHING SPEED NPN POWER TRANSISTORS
- HOLLOW EMITTER TECHNOLOGY
- HIGH VOLTAGE FOR OFF-LINE APPLICATIONS
- 50kHz SWITCHING SPEED
- LOW COST DRIVE CIRCUITS
- LOW DYNAMIC SATURATION

APPLICATIONS

- SMPS
- TV HORIZONTAL DEFLECTION

DESCRIPTION

Hollow emitter FASTSWITCH NPN power transistors are specially designed for 220V (and 117V with input doubler) off-line switching power supply and colour CRT deflection applications. Hollow emitter transistors can operate up to 50kHz with simple drive circuits which helps to simplify design and improve reliability. These transistors are suitable for application in flyback and forward low power converters, 140W to 250W. The high voltage rating of hollow emitter transistors can be used to advantage because a costly transformer clamp winding or over voltage snubbers can be omitted. When used in conjunction with a low voltage Power MOSFET in emitter switch configuration in flyback and forward converters, they can operate at up to 100kHz.

These hollow emitter FASTSWITCH transistors are available in TO-220, TO-218, ISOWATT220 and ISOWATT218 packages. The ISOWATT218 conforms to the creepage distance and isolation requirements of VDE, IEC, and UL specifications. Additionally these FASTSWITCH transistors are available in metal TO-3 packages.

TO-220   ISOWATT220   TO-218   ISOWATT218   TO-3
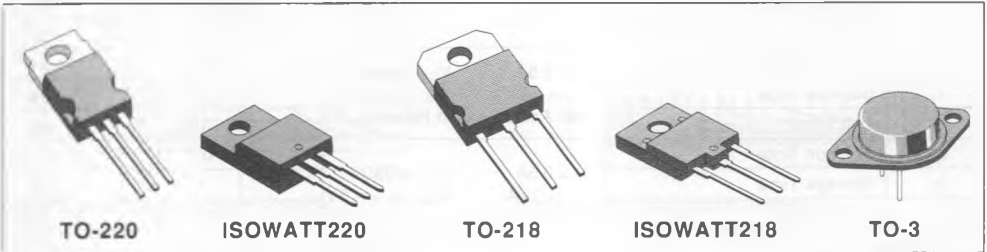
ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	SGS					Unit
		F344	IF344	F444	IF444	F544	
V_{CES}	Collector - Emitter Voltage ($V_{BE} = 0$)	1200					V
V_{CEO}	Collector - Emitter Voltage ($I_B = 0$)	600					V
V_{EBO}	Emitter - Base Voltage ($I_C = 0$)	7					V
I_C	Collector Current	7					A
I_{CM}	Collector Peak Current ($t_p < 5ms$)	12					A
I_B	Base Current	5					A
I_{BM}	Base Peak Current ($t_p < 5ms$)	8					A
P_{tot}	Total Dissipation at $T_c \leq 25°C$	85	40	95	55	115	W
T_{stg}	Storage Temperature – 65 to	150	150	150	150	175	°C
T_j	Junction Temperature	150	150	150	150	175	°C

THERMAL DATA

			SGS					
			F344	IF344	F444	IF444	F544	
$R_{thj-case}$	Thermal Resistance Junction-case	Max	1.47	3.12	1.31	2.27	1.3	°C/W

ELECTRICAL CHARACTERISTICS (T_{case} = 25°C unless otherwise specified)

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
I_{CES}	Collector Cutoff Current (V_{BE} = 0)	V_{CE} = 1200V				200	μA
I_{CEO}	Collector Cutoff Current (I_B = 0)	V_{CE} = 380V V_{CE} = 600V				200 2	μA mA
I_{EBO}	Emitter Cutoff Current (I_C = 0)	V_{EB} = 7V				1	mA
$V_{CEO (sus)}$*	Collector Emitter Sustaining Voltage	I_C = 0.1A		600			V
$V_{CE (sat)}$*	Collector Emitter Saturation Voltage	I_C = 3.5A I_C = 2.5A	I_B = 0.7A I_B = 0.35A			1.5 1.5	V V
$V_{BE (sat)}$*	Base Emitter Saturation Voltage	I_C = 3.5A I_C = 2.5A	I_B = 0.7A I_B = 0.35A			1.5 1.5	V V

RESISTIVE LOAD

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
t_{on}	Turn-on Time	I_C = 3.5A V_{CC} = 250V I_{B1} = 0.7A I_{B2} = − $2I_{B1}$			0.7	1.2	μs
t_s	Storage Time				2.2	3.5	μs
t_f	Fall Time				0.18	0.3	μs
t_{on}	Turn-on Time	I_C = 3.5A V_{CC} = 250V I_{B1} = 0.7A I_{B2} = − $2I_{B1}$ with Antisaturation Network			0.7		μs
t_s	Storage Time				1.5		μs
t_f	Fall Time				0.2		μs
t_{on}	Turn-on Time	I_C = 3.5A V_{CC} = 250V I_{B1} = 0.7A $V_{BE(off)}$ = − 5V			0.7		μs
t_s	Storage Time				1		μs
t_f	Fall Time				0.2		μs

INDUCTIVE LOAD

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
t_s	Storage Time	I_C = 3.5A V_{CL} = 450V L = 300μH	h_{FE} = 5 $V_{BE(off)}$ = − 5V $R_{B(off)}$ = 1.2Ω		1.4	2.8	μs
t_f	Fall Time				0.1	0.2	μs
t_s	Storage Time	I_C = 3.5A V_{CL} = 450V L = 300μH T_c = 100°C	h_{FE} = 5 $V_{BE(off)}$ = − 5V $R_{B(off)}$ = 1.2Ω			4	μs
t_f	Fall Time					0.3	μs

* Pulsed : Pulse duration = 300μs. duty cycle = 1.5%
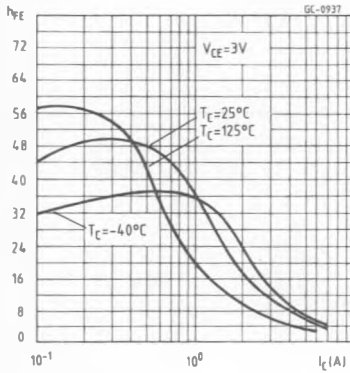
SGS-THOMSON
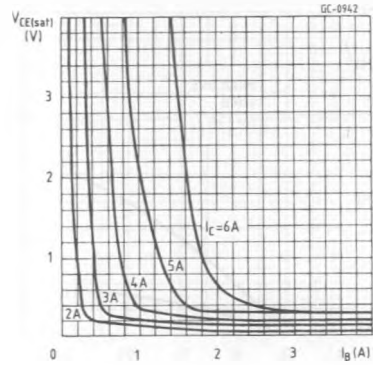MICROELECTRONICS

Safe Operating Areas
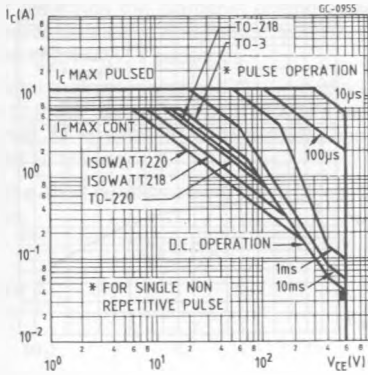
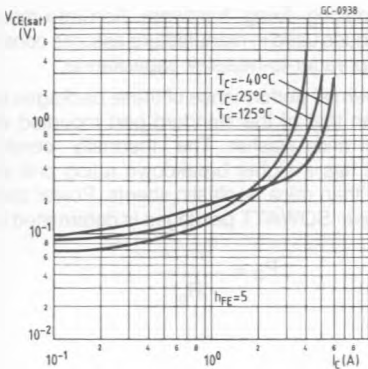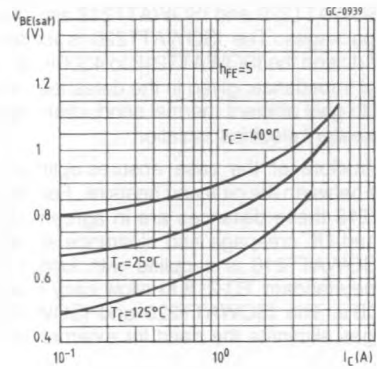## Reverse Biased Safe Operating Area
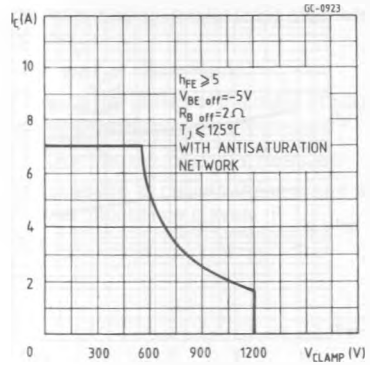
DC Current Gain

Collector-emitter Saturation Voltage

Collector-emitter Saturation Voltage

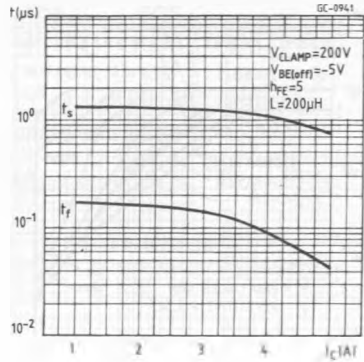

Base-emitter Saturation Voltage

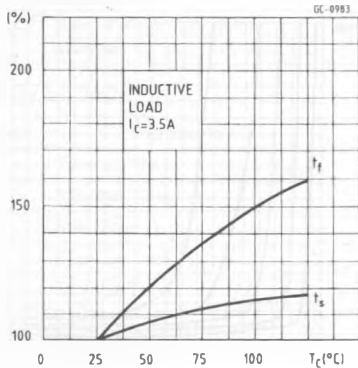
SGS-THOMSON
MICROELECTRONICS

Resistive Load Switching Times
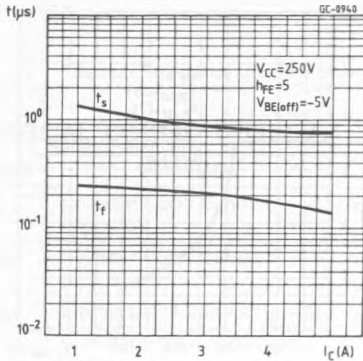
Inductive Load Switching Times

Switching Times Percentance Variation

ISOWATT PACKAGES CHARACTERISTICS AND APPLICATION

The ISOWATT220 and ISOWATT218 are fully isolated packages. The ISOWATT220 is isolated to 2000V dc and the ISOWATT218 to 4000V dc. Their thermal impedance, given in the datasheet, is optimised to give efficient thermal conduction together with excellent electrical isolation.

The structure of the case ensures optimum distances between the pins and heatsink. For the ISOWATT218 these distances are in agreement with VDE and UL creepage and clearance standards. The ISOWATT218 is supplied with longer leads than the standard TO-218 to allow easy mounting on PCB's. The ISOWATT220 and ISOWATT218 packages eliminate the need for external isolation

so reducing fixing hardware. Accurate moulding techniques used in manufacture assures consistent heat spreader-to-heatsink capacitance.

The thermal performance of these packages is better than that of the standard part mounted with a 0.1mm mica washer. The thermally conductive plastic has a higher breakdown rating and is less fragile than mica or plastic sheets. Power derating for these ISOWATT packages is determined by :

$$P_D = \frac{T_j - T_c}{R_{th}}$$

SGS-THOMSON
MICROELECTRONICS

THERMAL IMPEDANCE OF ISOWATT PACKAGES

Fig. 1 illustrates the elements contributing to the thermal resistance of a transistor heatsink assembly, using ISOWATT packages.

The total thermal resistance $R_{th(tot)}$ is the sum of each of these elements. The transient thermal impedance, Z_{th} for different pulse durations can be estimated as follows :

1 - For a short duration power pulse of less than 1ms :

$$Z_{th} < R_{thJ-C}$$

2 - For an intermediate power pulse of 5ms to 50ms seconds :

$$Z_{th} = R_{thJ-C}$$

3 - For long power pulses of the order of 500ms seconds or greater :

$$Z_{th} = R_{thJ-C} + R_{thC-HS} + R_{thHS-amb}$$

It is often possible to discern these areas on transient thermal impedance curves.

Figure 1.

$$R_{thJ-C} \quad R_{thC-HS} \quad R_{thHS-amb}$$